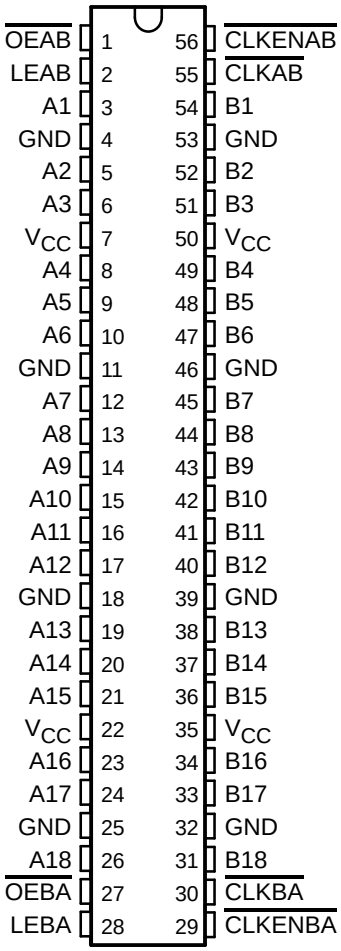
- **Member of the Texas Instruments *Widebus*™ Family**
- ***UBT*™ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **Designed to Facilitate Incident-Wave Switching for Line Impedances of 50 Ω or Greater**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Bus-Hold On Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages**

DGG OR DL PACKAGE
(TOP VIEW)



description

This 18-bit universal bus transceiver is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74ALVC16600 combines D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latch-enable (LEAB and LEBA), and clock ($\overline{CLKAB}$ and $\overline{CLKBA}$) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if $\overline{CLKAB}$ is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the high-to-low transition of $\overline{CLKAB}$. Output enable $\overline{OEAB}$ is active low. When $\overline{OEAB}$ is low, the outputs are active. When $\overline{OEAB}$ is high, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses $\overline{OEBA}$, LEBA, $\overline{CLKBA}$, and $\overline{CLKENBA}$.

The SN74ALVC16600 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVC16600 is characterized for operation from –40°C to 85°C.

PRODUCT PREVIEW

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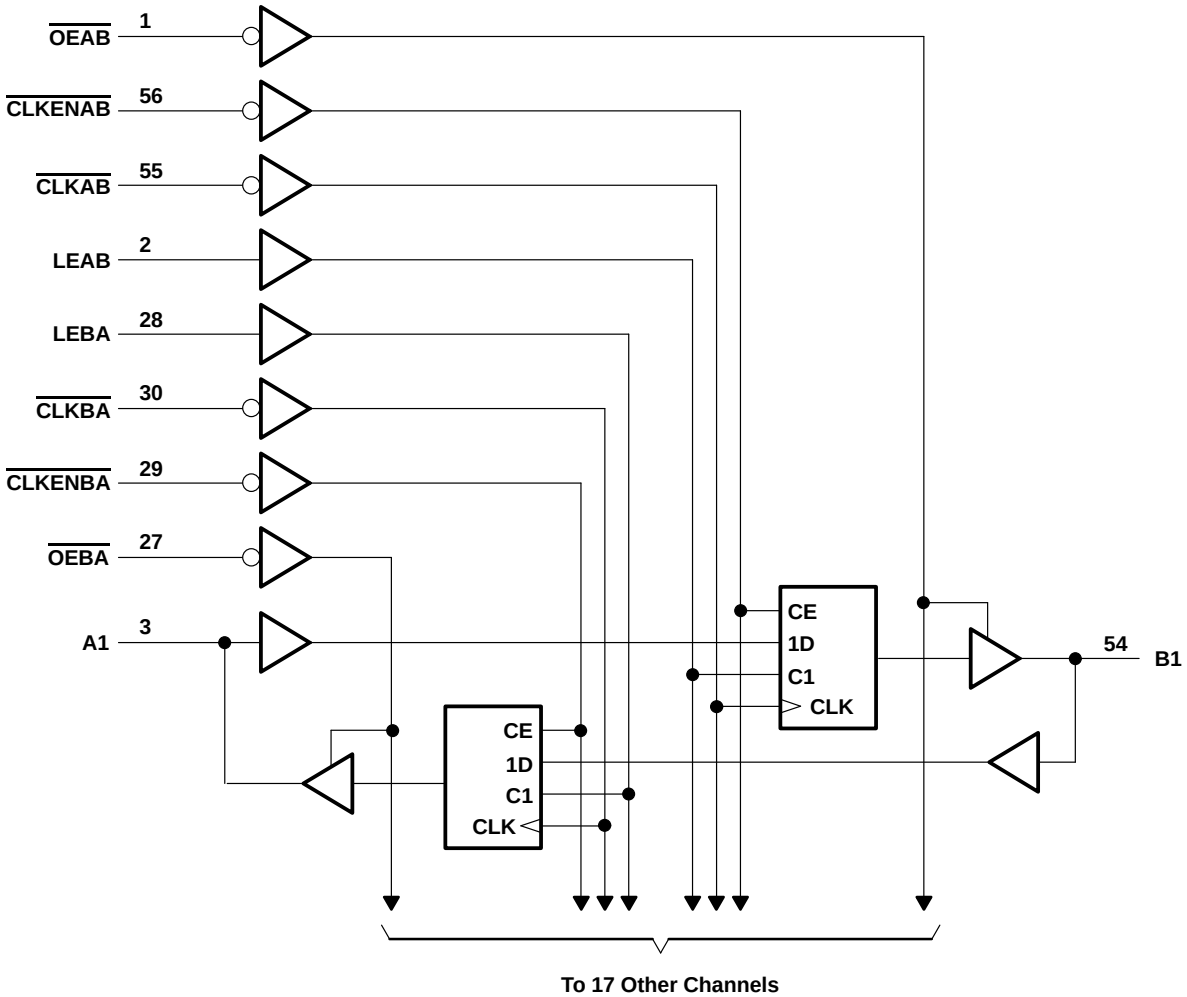
FUNCTION TABLE†

INPUTS					OUTPUT
$\overline{\text{CLKENAB}}$	$\overline{\text{OEAB}}$	LEAB	$\overline{\text{CLKAB}}$	A	B
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0‡
H	L	L	X	X	B_0‡
L	L	L	↓	L	L
L	L	L	↓	H	H
L	L	L	H	X	B_0‡
L	L	L	L	X	B_0§

† A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{\text{OEBA}}$, LEBA, $\overline{\text{CLKBA}}$, and $\overline{\text{CLKENBA}}$.
‡ Output level before the indicated steady-state input conditions were established.
§ Output level before the indicated steady-state input conditions were established, provided that $\overline{\text{CLKAB}}$ was low before LEAB went low.

PRODUCT PREVIEW

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (except I/O ports) (see Note 1) . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (I/O ports) (see Notes 1 and 2) . . . . . –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Notes 1 and 2) . . . . . –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . –50 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±100 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 3): DGG package . . . . . 1 W
DL package . . . . . 1.4 W
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note.

recommended operating conditions

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 2.7 V to 3.6 V	2		V
V_{IL}	Low-level input voltage	V_{CC} = 2.7 V to 3.6 V		0.8	V
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2.7 V		–12	mA
		V_{CC} = 3 V		–24	
I_{OL}	Low-level output current	V_{CC} = 2.7 V		12	mA
		V_{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	10	ns/V
T_A	Operating free-air temperature		–40	85	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}†	MIN	MAX	UNIT
V_{OH}		I_{OH} = –100 μA	MIN to MAX	V_{CC}–0.2		V
		I_{OH} = –12 mA	2.7 V	2.2		
			3 V	2.4		
		I_{OH} = –24 mA	3 V	2		
V_{OL}		I_{OL} = 100 μA	MIN to MAX		0.2	V
		I_{OL} = 12 mA	2.7 V		0.4	
		I_{OL} = 24 mA	3 V		0.55	
I_I		$V_I = V_{CC}$ or GND	3.6 V		±5	μA
$I_{I(hold)}$	Data I/Os	V_I = 0.8 V	3 V	75		μA
		V_I = 2 V		–75		
I_{OZ}‡		$V_O = V_{CC}$ or GND	3.6 V		±10	μA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	3.6 V		40	μA
ΔI_{CC}		V_{CC} = 3 V to 3.6 V, One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND			750	μA
C_i	Control inputs	$V_I = V_{CC}$ or GND	3.3 V			pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	3.3 V			pF

† For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

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